

Title (en)

MONITORING A LASER MACHINING PROCESS USING DEEP FOLDING NEURAL NETWORKS

Title (de)

ÜBERWACHUNG EINES LASERARBEITUNGSPROZESSES MITHILFE VON TIEFEN FALTENDEN NEURONALEN NETZEN

Title (fr)

SURVEILLANCE D'UN PROCESSUS D'USINAGE LASER À L'AIDE DE RÉSEAUX DE NEURONES ARTIFICIELS PLIANTS PROFONDS

Publication

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Application

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Abstract (en)

[origin: WO2020104103A1] The invention relates to a system for monitoring a laser machining process for machining a workpiece, comprising: a computing unit which is designed to determine an input tensor on the basis of current data of the laser machining process and to determine an output tensor on the basis of the input tensor using a transmission function, said output tensor containing information on a current machining result, wherein the transmission function between the input tensor and the output tensor is formed by a trained neural network.

IPC 8 full level

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